

A

B

C

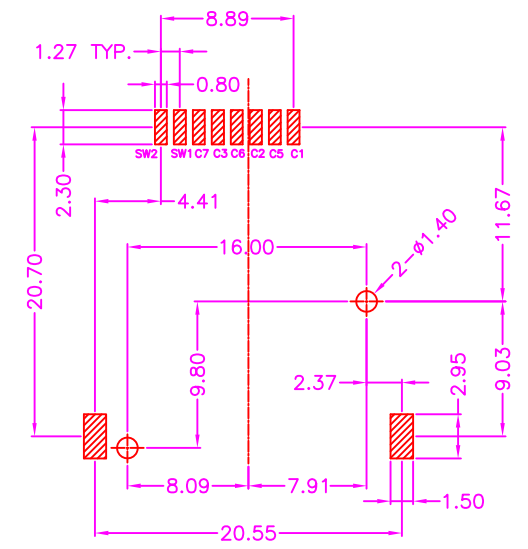
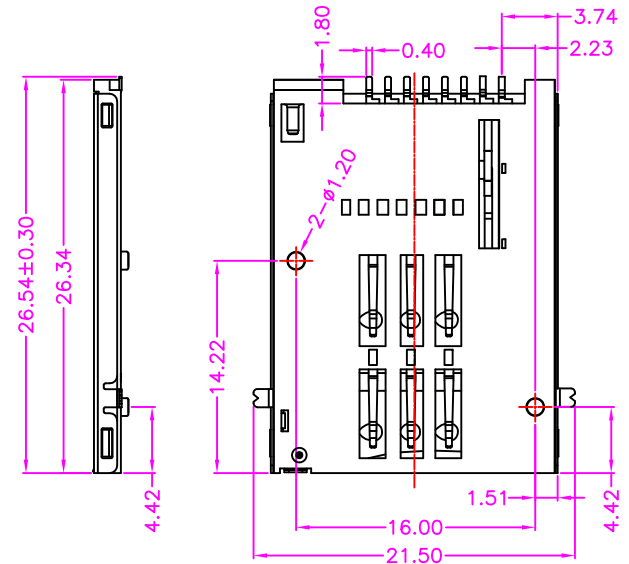
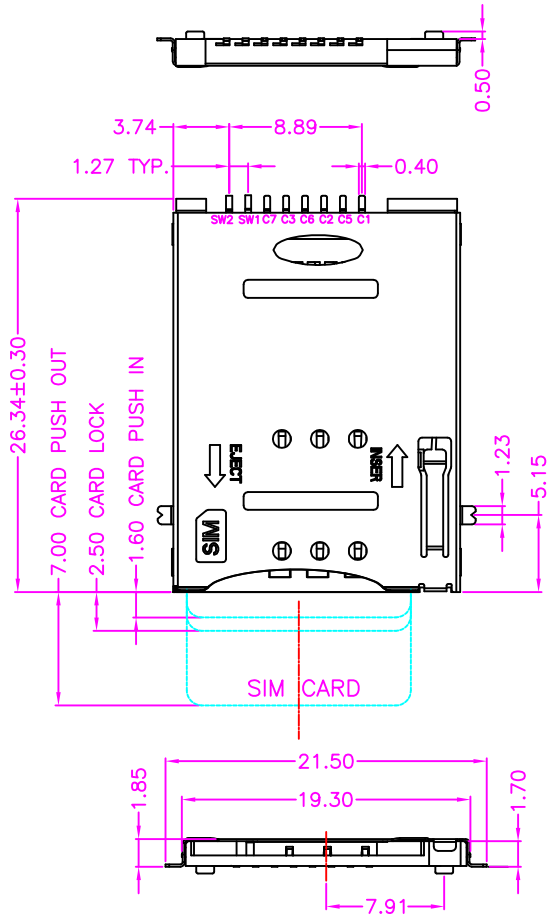
D

A

B

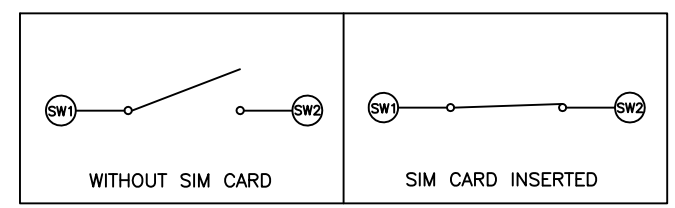
C

D



P.C.B. LAYOUT TOP VIEW ±0.05

▨ SOLDER AREA



**MATERIALS**

HOUSING: HI-TEMP. PLASTIC (UL 94V-0)  
 SHELL: STAINLESS STEEL, NICKEL PLATING  
 SOLDER PAD: GOLD PLATING  
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA  
 TIN PLATING ON SOLDER TAIL

**SPECIFICATION**

CURRENT RATING: 0.5 AMP MAX  
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE  
 CONTACT RESISTANCE: 100m OHMS MAX  
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V  
 OPERATION TEMPERATURE: -40°C~+85°C

**PART NUMBER:**

MMCPD - 0 8 \* T - 1 2 A

SERIES  
 NO. OF POS.  
 CONTACT PLATED OPTION  
 T  
 TAPE REEL PACKAGE  
 TIN PLATING ON SOLDER TAIL

- 1: GOLD FLASH
- 3: 3u" GOLD
- 5: 5u" GOLD
- 6: 10u" GOLD
- 9: 30u" GOLD

PIN	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



TOLERANCES

X.±0.40	.XX±0.20
.X±0.30	.XXX±0.10

REV.	A	DRAWN BY	Zhong 2021/12/27	TITLE	SIM CARD, 8PIN, PCB MOUNT, SMT, METAL SHIELD, PUSH-PUSH TYPE				
		APPROVED BY	Lion 2021/12/27	DRAW NO.	MMCPD-010	UNIT	MM	Sheet	1/1